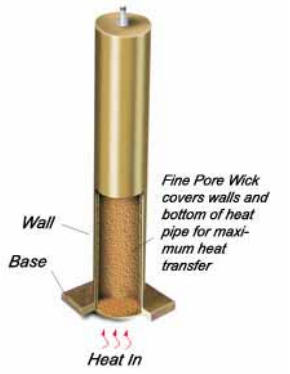
Thermal Transtech International Corporation

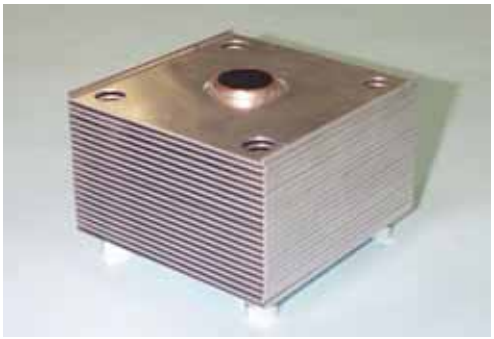
HEAT COLUMN

In a Heat column the base is an integral part of the heat pipe. By having wick structure in the base, a significant thermal interface between the heat source and the air is eliminated, and higher heat flux loads can be handled. The vertical arrangement of cooling fins along the outside of the heat pipe results in maximum heat dissipation with the smallest footprint.

The Heat column example presented here is a compact forced convection heat sink designed to cool a 116 watt processor module at 0.265°C per watt. TTIC's wicked base structure will handle higher heat loads, and the heat sink design of the stacked fins provides exceptional cooling in a small footprint.



Detail of Heat Column



Heat Column Heat sink

TTIC Heat Column	Φ25.4X70mm
TTV Power	116 W
Heat sink inlet ambient	22.7°C
CPU case temperature	53.4°C
TTV thermal resistance	0.265

TTIC Heat Column & Heat sink